

S/N 09/941,476

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

PATENT

Applicant: John Whitman

Examiner: Kevin P. Shortle

Serial No.: 09/941,476

Group Art Unit: 1734

Filed: August 29, 2001

Docket: 303.254US4

Title: A SOLVENT PREWET AND METHOD TO DISPENSE THE SOLVENT
PREWET

RECEIVED

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

MAY 06 2002

TC 1700

Commissioner for Patents
Washington, D.C. 20231

Applicant has reviewed the Office Action mailed on January 22, 2002. Please amend the above-identified patent application as follows.

COPY OF PAPERS
ORIGINALLY FILED

IN THE SPECIFICATION

Please make the paragraph substitutions indicated in the appendix entitled Clean Version of Amended Specification Paragraphs. The specific changes incorporated in the substitute paragraphs are shown in the following marked-up versions of the original paragraphs.

The paragraph beginning at page 2, line 20 is amended as follows:

After several preliminary preparation steps, a wafer is ready to be coated with photoresist. The goal of the coating step is to produce a uniform, adherent, defect-free polymeric film of desired thickness over the entire wafer. Spin coating is by far the most widely used technique to apply such films. This procedure is carried out by dispensing the resist solution onto the wafer surface, and then rapidly spinning the wafer until the resist is essentially dry. In order to maintain [reprodu ible] reproducible line width in VLSI fabrication applications, resist film uniformity across the wafer (and from wafer to wafer) should be within +/- 100 angstroms.

IN THE CLAIMS

Please amend claims 20-21, 38-39, 41, 50-57 and 59 by substituting the claim set in the appendix entitled Clean Version of Pending Claims for the previously pending claim set. The substitute claim set is intended to reflect amendment of previously pending claims 20-21, 38-39, 41, 50-57 and 59. The specific amendments to individual claims are detailed in the following marked up set of claims.